TOSHIBA SG4000GXH26G

TOSHIBA GATE TURN-OFF THYRISTOR LOW SNUBBER TYPE

S G 4 0 0 0 G X H 2 6 G

INVERTER APPLICATION

Unit in mm

Repetitive Peak off-state Voltage: VDRM = 4500 V (Note 1)

R.M.S On-State Current $: I_{T(RMS)} = 1200 A$

 $(T_f = 76^{\circ}C)$

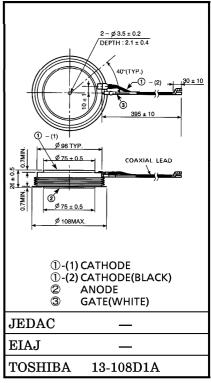
Peak Turn-Off Current : $I_{TGQM} = 4000 A$

Critical Rate of Rise of On-State Current : $di/dt = 500 \text{ A}/\mu\text{s}$

Critical Rate of Rise of off-State Voltage $: dv/dt = 1000 \text{ V}/\mu\text{s}$

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL RATING		UNIT	
Repetitive Peak Off-state Voltage (Note 1)	$v_{ m DRM}$	4500	V	
Repetitive Peak Reverse Voltage	v_{RRM}	RM 16		
Peak Turn-Off Current (Note 2)	I_{TGQM}	4000 (6 μF) 3000 (3 μF)	Α	
R.M.S On-State Current (Note 3)	I _T (RMS)	1200	A	
Peak One Cycle Surge On-State Current (non repetitive, 10 ms width half sine waveform)	I_{TSM}	20000	A	
Critical Rate Of Rise Of On-State Current (Note 4)	di / dt	500	A/μs	
Peak Forward Gate Current	I_{FGM}	100	A	
Average Forward Gate Power Dissipation	P _{FG (AV)}	50	W	
Average Reverse Gate Power Dissipation	P _{RG} (AV)	250	W	
R.M.S Gate Current (Note 5)	I _G (RMS)	42	Α	
Peak Reverse Gate Voltage (at Static)	v_{RGM}	16	V	
Operating Junction Temperature Range	T_{j}	-40~125	°C	
Storage Temperature Range	$T_{ m stg}$	-40~150	°C	
Mounting Force	_	33.3±4.9	kN	



Weight: 1290 g

(Note 1): $V_{GK} = -2 V$

(Note 2) : $V_{DM} = 4000 \, \text{V}, \, C_S = 6 \, \mu \text{F} \, \text{or} \, 3 \, \mu \text{F}, \, R_S = 5 \, \Omega, \, di_{GQ} / \, dt = 50 \, \text{A} / \, \mu \text{s}, \, V_{DSP} \leq 1000 \, \text{V*}, \, L_S \leq 0.2 \, \mu \text{H} \, * \underline{\text{FOR}} \, 3 \, \mu \text{F-} 3000 \, \text{A}, \, 1200 \, \text{V} \, \, \text{FOR} \, 6 \, \mu \text{F-} 4000 \, \text{A}$

(Note 3): 50 Hz Half Sine Waveform at Tf = 76°C

(Note 4) : $V_D = 1/2 V_{DRM}$, $I_{GM} = 25 A$

(Note 5): Ambient Temperature of coaxial gate-cathode lead = 90°C

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ELECTRICAL CARACTERISTICS

ELLCTRICAL CARACTERISTICS							
CHARACTERISTICS	SYMBOL	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
Repetitive Peak Off-State Current	$I_{ m DRM}$	$V_{\mathrm{DRM}} = \mathrm{RATED}, \ V_{\mathrm{GK}} = -2 \mathrm{V}, \ T_{\mathrm{j}} = 125 ^{\circ} \mathrm{C}$				100	mA
Repetitive Peak Reverse Current	I_{RRM}	$V_{RRM} = RATED, T_j = 125$ °C		_	_	10	mA
Repetitive Peak Reverse Gate Current	$I_{ m RGM}$	$V_{ m RGM} = 16 \ m V, \ T_j = 125 m ^{\circ} C$			_	10	
Peak On-State Voltage	$V_{ extbf{TM}}$	$I_{TM} = 3000 \text{ A}, T_j = 125^{\circ}\text{C}$			_	4.0	V
Gate Trigger Voltage	v_{GT}		$T_j = -40^{\circ}C$		_	1.70	-1 V I
		$egin{aligned} \mathbf{V_D} &= 24 \mathrm{V}, \\ \mathbf{R_L} &= 0.1 \Omega \end{aligned}$	$T_{\rm j}=25^{\circ}{ m C}$		_ _	1.50	
Gate Trigger Current	I_{GT}		$T_j = 0$ °C		_	8.5	
			$T_j = 25$ °C	_	_	3.5	
Turn-On Delay Time	^t d	$V_{D} = 1/2 V_{DRM},$ $di/dt = 500 A/\mu s,$ $I_{GM} = 25 A,$ $T_{j} = 25^{\circ}C$			_	3	μ s
Turn-On Time	tgt			_	_	10	
Critical Rate of Rise of Off- State Voltage	dv / dt	$V_{DRM} = 2/3 \text{ RATED},$ $T_j = 125$ °C, $V_{GK} = -2 \text{ V}$		1000	_	_	V/μs
Storage Time	t_S	$\begin{split} &I_{TGQ} = 4000 \text{ A}, \text{ V}_{DM} = 4000 \text{ V}, \\ &V_{D} = 2250 \text{ V}, \\ &\text{di}_{GQ} / \text{dt} = 50 \text{ A} / \mu\text{s}, \\ &C_{S} = 6 \mu\text{F}, \text{ R}_{S} = 5 \Omega, \\ &T_{j} = 125 ^{\circ}\text{C}, \text{ L}_{S} \leqq 0.2 \mu\text{H} \end{split}$		_	_	30	μs
Gate Turn-Off Time	${ m t_{gq}}$			_	_	32	
Tail Time	t _{tail}			_	_	150	
Gate Turn-Off Current	$I_{\mathbf{GQ}}$			_	850	_	A
Thermal Resistance (Junction to Fin)	R _{th (j-f)}	DC		_	_	0.014	°C/W

